

Silicon Turnkey Solutions (STS) and UAF/OEM (University of Alaska Fairbanks' Office of Electronic Miniaturization), an Authorized licensee of Tesseract Inc.' stacking technology, have entered into an exclusive agreement to supply High Reliability 3D stacked Products to Military/Space customers

Fremont, California, January 25, 2007.... Silicon Turnkey Solutions (STS) and University of Alaska Fairbanks' Office of Electronic Miniaturization (UAF/OEM) have formed an exclusive, collaborative partnership to introduce and supply high speed and high density memory modules and Systems-on-Package (SOP) products to Aerospace and DOD customers utilizing Tesseract's CSP and stacking technology. UAF is an authorized licensee of Tesseract.

Under this agreement, the CSP/stack assembly operations will take place at UAF and STS will perform design, applications engineering, test/characterization, and qualification to supply finished products to its customers.

"We are extremely excited on our association with UAF" said Zef Malik, President & CEO of STS. This relationship brings technical synergy to deploy advanced high reliability, high density packaging, with the smallest form factor solutions.

"STS is collaborative partner and solution provider to our key customers that face increasing challenges in integration with higher speed and high density, small form factor products to built reliable systems. This arrangement with UAF allow STS to use already proven high volume manufacturability and reliable 3D stacking technology to introduce series of products and services to our Military/Space customers".

The companies are expected to embark on joint announcements of product types and configuration and start offering the products upon successful completion of Qualification tests.

More details about products and agreement please contact:

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About STS:

Silicon Turnkey Solutions (STS) is privately held, completely U.S.A. based company; headquartered at 801 Buckeye Court, Milpitas, CA. 95053. STS is a collaborative partner with complete in house, manufacturing, testing, environmental screening and product design/ qualification capabilities that integrates its engineering expertise in supplying latest technology high reliability products with test validation and characterization services

About UAF/OEM:

University of Alaska Fairbanks' Office of Electronic Miniaturization (UAF/OEM) was established in the spring of 2004 and facilitates, supports, conducts, and integrates research in the area of electronic miniaturization. It runs a pilot line for chip scale packages in its 1,530 sq. ft. certified clean room, and within its lab complex at 3330 Industrial Avenue, Fairbanks, AK 99701, it specializes in projects involving design, engineering, prototyping, testing, modeling and pilot manufacturing of miniaturized electronic systems (Multi Chip Module (MCM), System in a Package (SiP), High Density Boards, Stacked Circuits, Dense Electronics, and nano composites applicable to ultra high value capacitors or electronics, energy storage applications, microscopic high value inductors, photovoltaics, broad band sensors, spectrally selective sensors, plasmonics, nanointerconnects, system ground planes, and EMI shielding.